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10075566
JC997 U.S. PTO

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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10075566	02/13/2002	134	003	1746	CHAUDHRY

**APPLICANTS: Aoki Hidemitsu; Yamasaki Shinya;

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**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A DIV OF 09/313,027 05/17/1999

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 10-138365 05/20/1998

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 12688A
TITLE : Method for cleaning semiconductor wafer after chemical mechanical polishing on copper wiring U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		Application Examiner		
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